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# INTERNATIONAL STANDARD

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**Semiconductor devices – Mechanical and climatic test methods –  
Part 9: Permanence of marking**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## CONTENTS

|                               |   |
|-------------------------------|---|
| FOREWORD.....                 | 3 |
| 1 Scope.....                  | 5 |
| 2 Normative references .....  | 5 |
| 3 Terms and definitions ..... | 5 |
| 4 Equipment .....             | 6 |
| 5 Safety precautions.....     | 7 |
| 6 Procedure.....              | 7 |
| 6.1 Solvents test.....        | 7 |
| 6.2 Tape pull test.....       | 7 |
| 7 Failure criteria .....      | 8 |
| 8 Summary .....               | 8 |
| Bibliography.....             | 9 |

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**SEMICONDUCTOR DEVICES –  
MECHANICAL AND CLIMATIC TEST METHODS –****Part 9: Permanence of marking**

## FOREWORD

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International Standard IEC 60749-9 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) revision to Clause 4 Equipment by a complete rewriting of Clause 3 Terms and definitions;
- b) additional variant – ‘adhesive tape pull test’.

The text of this standard is based on the following documents:

| FDIS         | Report on voting |
|--------------|------------------|
| 47/2348/FDIS | 47/2373/RVD      |

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

# SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

## Part 9: Permanence of marking

### 1 Scope

The purpose of this part of IEC 60749 is to determine whether the marks on solid state semiconductor devices will remain legible when subjected to the application and removal of labels or the use of solvents and cleaning solutions commonly used during the removal of solder flux residue from the printed circuit board manufacturing process.

This test is applicable for all package types. It is suitable for use in qualification and/or process monitor testing. The test is considered non-destructive. Electrical or mechanical rejects can be used for the purpose of this test.

NOTE 1 This procedure does not apply to laser branded packages.

Many available solvents that could be used are either not sufficiently active, too stringent, or even dangerous to humans when in direct contact or when fumes are inhaled.

NOTE 2 The composition of solvents used in this document is considered typical and representative of the desired stringency as far as the usual coatings and markings are concerned.

### 2 Normative references

There are no normative references in this document.